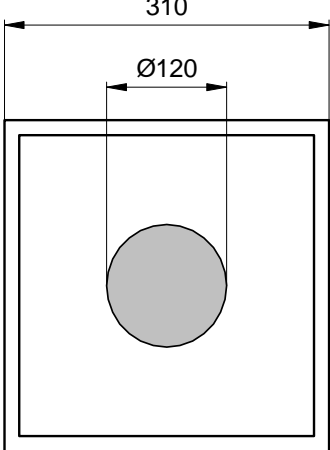


| Radiation  | Type     | Technology   | Electrodes   |
|------------|----------|--------------|--------------|
| Red-orange | Standard | AllnGaP/GaAs | P (anode) up |

|   |   |  |
|---|---|--|
|  | typ. dimensions ( $\mu\text{m}$ )   |  |
|   | <u>typ. thickness</u><br>260 ( $\pm 20$ ) $\mu\text{m}$<br><br><u>anode</u><br>gold alloy, 1.5 $\mu\text{m}$<br><br><u>cathode</u><br>gold alloy, 0.5 $\mu\text{m}$ |  |

### Optical and Electrical Characteristics

$T_{\text{amb}} = 25^\circ\text{C}$ , unless otherwise specified

| Parameter                        | Test conditions        | Symbol                | Min | Typ | Max | Unit |
|----------------------------------|------------------------|-----------------------|-----|-----|-----|------|
| Forward voltage                  | $I_F = 20 \text{ mA}$  | $V_F$                 | 1.6 | 2.0 | 2.4 | V    |
| Reverse voltage                  | $I_R = 10 \mu\text{A}$ | $V_R$                 | 5   |     |     | V    |
| Radiant power <sup>1</sup>       | $I_F = 20 \text{ mA}$  | $\Phi_e$              | 1.4 | 1.8 | 2.5 | mW   |
| Luminous intensity <sup>2</sup>  | $I_F = 20 \text{ mA}$  | $I_v$                 |     | 100 |     | mcd  |
| Peak wavelength                  | $I_F = 20 \text{ mA}$  | $\lambda_P$           | 610 | 619 | 630 | nm   |
| Dominant wavelength <sup>2</sup> | $I_F = 20 \text{ mA}$  | $\lambda_D$           | 600 | 612 | 630 | nm   |
| Spectral bandwidth at 50%        | $I_F = 20 \text{ mA}$  | $\Delta\lambda_{0.5}$ | 10  | 20  | 30  | nm   |
| Switching time                   | $I_F = 20 \text{ mA}$  | $t_r, t_f$            | 15  | 20  | 30  | ns   |

<sup>1</sup>measured on bare chip on TO-18 header with *EPIGAP* equipment

<sup>2</sup>for information only

### Labeling

| Type       | Lot N° | $I_v(\text{typ})$ [mcd] | $V_F(\text{typ})$ [V] | Quantity |
|------------|--------|-------------------------|-----------------------|----------|
| ELC-619-14 |        |                         |                       |          |

**Packing:** Chips on adhesive film with wire-bond side on top

We reserve the right to make changes to improve technical design and may do so without further notice. Parameters can vary in different applications. All operating parameters must be validated for each application by the customers themselves.